

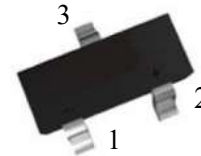
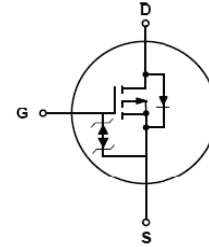
P-Channel Enhancement Mode MOSFET

$R_{DS(ON)} \cong 1.2 \Omega @ V_{GS} = -4.5 \text{ V}$

$R_{DS(ON)} \cong 1.5 \Omega @ V_{GS} = -2.5 \text{ V}$

$BV \cong -20 \text{ V}$ $P_{tot} \cong 0.83 \text{ W}$ $I_D \cong -0.67 \text{ A}$

SOT-23



1: Gate 2: Source 3: Drain

Features

- Surface-mounted package
- Extremely low threshold voltage
- Advanced trench cell design
- ESD protected

Applications

- Portable appliances

Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_A = 25 \text{ }^\circ\text{C}$	-	-20	V
V_{GS}	Gate-Source Voltage	$T_A = 25 \text{ }^\circ\text{C}$	-	± 10	V
I_D^*	Drain Current	$T_A = 25 \text{ }^\circ\text{C}, V_{GS} = -4.5 \text{ V}$	-	-0.67	A
I_{DM}^{***}	Pulsed Drain Current	$T_A = 25 \text{ }^\circ\text{C}, V_{GS} = -4.5 \text{ V}$	-	-2.6	A
P_{tot}^*	Total Power Dissipation	$T_A = 25 \text{ }^\circ\text{C}$	-	0.83	W
		$T_A = 100 \text{ }^\circ\text{C}$	-	0.33	
T_{stg}	Storage Temperature		-55	150	$^\circ\text{C}$
T_J	Junction Temperature		-	150	$^\circ\text{C}$
I_S^*	Diode Forward Current	$T_A = 25 \text{ }^\circ\text{C}$	-	-2.6	A
$R_{\theta JA}^*$	Thermal Resistance- Junction to Ambient		-	150	$^\circ\text{C} / \text{W}$

Notes: * Surface Mounted on 1 in^2 pad area, $t \leq 10 \text{ sec}$

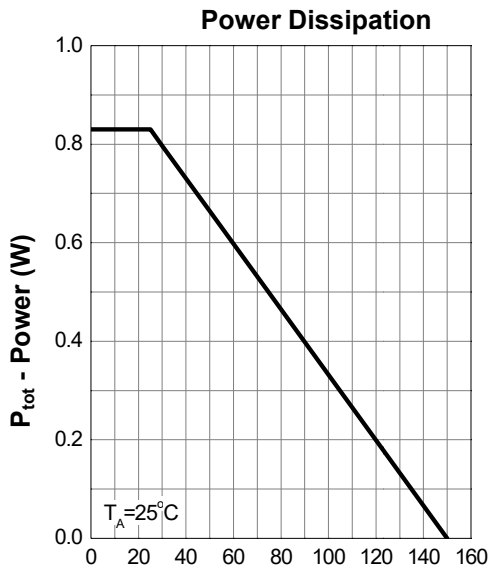
** Pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$

Electrical Characteristics (Ta = 25 °C Unless Otherwise Noted)

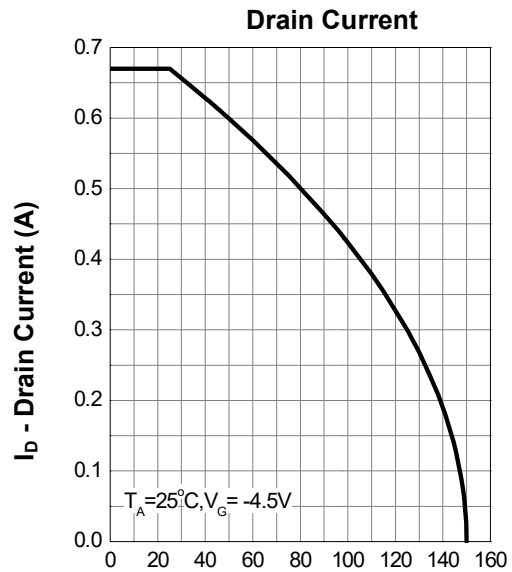
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_{DS} = -250\ \mu\text{A}$	-20	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = -250\ \mu\text{A}$	-0.3	-0.65	-1.0	V
I_{DSS}	Drain Leakage Current	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}$	-	-	-1	μA
		$T_J = 85\text{ }^\circ\text{C}$	-	-	-30	μA
I_{GSS}	Gate Leakage Current	$V_{GS} = \pm 8\text{ V}, V_{DS} = 0\text{ V}$	-	-	± 10	μA
$R_{DS(ON)}^a$	On-State Resistance	$V_{GS} = -4.5\text{ V}, I_{DS} = -0.5\text{ A}$	-	0.85	1.2	Ω
		$V_{GS} = -2.5\text{ V}, I_{DS} = -0.2\text{ A}$	-	1.05	1.5	
		$V_{GS} = -1.5\text{ V}, I_{DS} = -0.04\text{ A}$	-	1.5	-	
		$V_{GS} = -1.2\text{ V}, I_{DS} = -0.01\text{ A}$	-	2	-	
Diode Characteristics						
V_{SD}^a	Diode Forward Voltage	$I_{SD} = -0.5\text{ A}, V_{GS} = 0\text{ V}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD} = -0.5\text{ A}, dI_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	70	-	ns
Q_{rr}	Reverse Recovery Charge		-	68	-	nC
Dynamic Characteristics^b						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = -10\text{ V}$ Frequency = 1 MHz	-	87	-	pF
C_{oss}	Output Capacitance		-	15	-	
C_{rss}	Reverse Transfer Capacitance		-	8.2	-	
$t_d(on)$	Turn-on Delay Time	$V_{DS} = -30\text{ V}, V_{GEN} = -10\text{ V},$ $R_G = 25\ \Omega, R_L = 60\ \Omega,$ $I_{DS} = -0.67\text{ A}$	-	5.6	-	ns
t_r	Turn-on Rise Time		-	5.3	-	
$t_d(off)$	Turn-off Delay Time		-	30	-	
t_f	Turn-off Fall Time		-	21	-	
Q_g	Total Gate Charge	$V_{GS} = -4.5\text{ V}, V_{DS} = -10\text{ V},$ $I_{DS} = -0.67\text{ A}$	-	1.8	-	pC
Q_{gs}	Gate-Source Charge		-	0.82	-	
Q_{gd}	Gate-Drain Charge		-	0.59	-	

 Notes: a : Pulse test ; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$

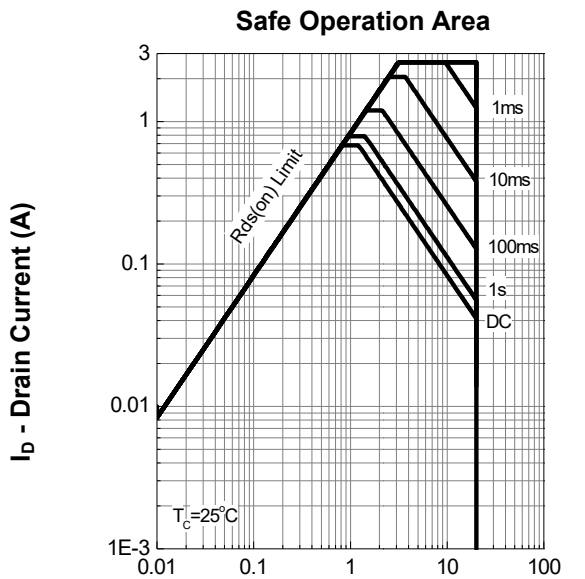
b : Guaranteed by design, not subject to production testing



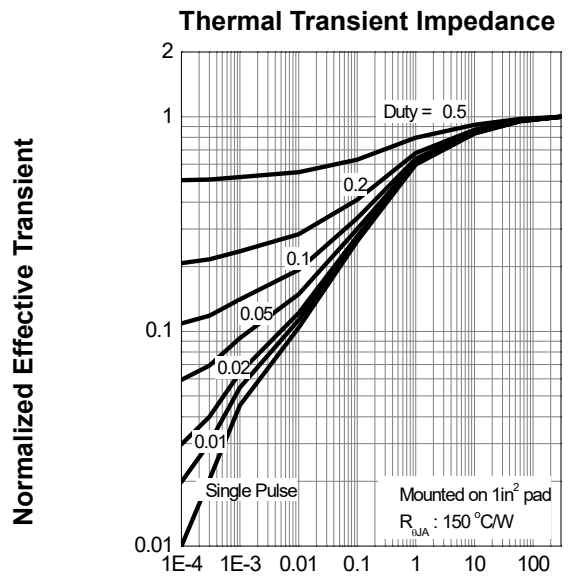
T_j - Junction Temperature (° C)



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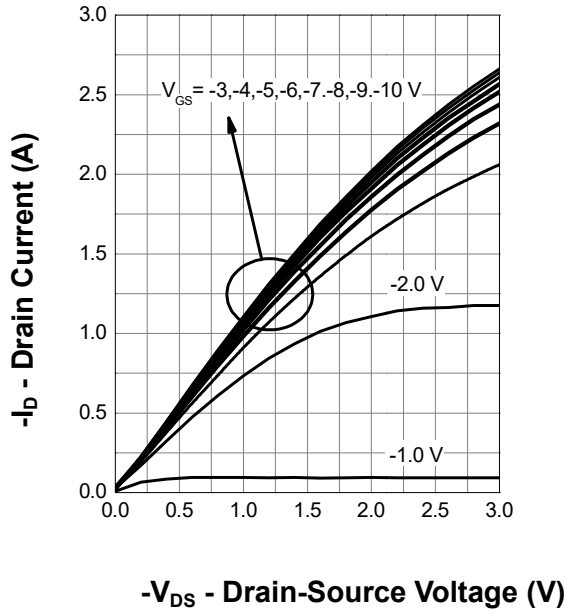


$-V_{DS}$ - Drain-Source Voltage (V)

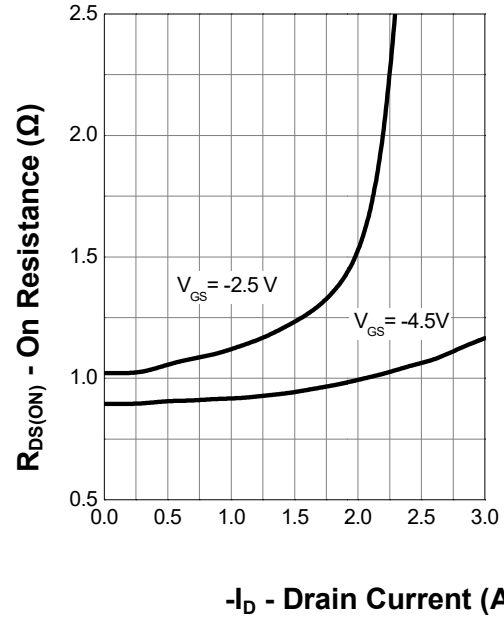


Square Wave Pulse Duration (sec)

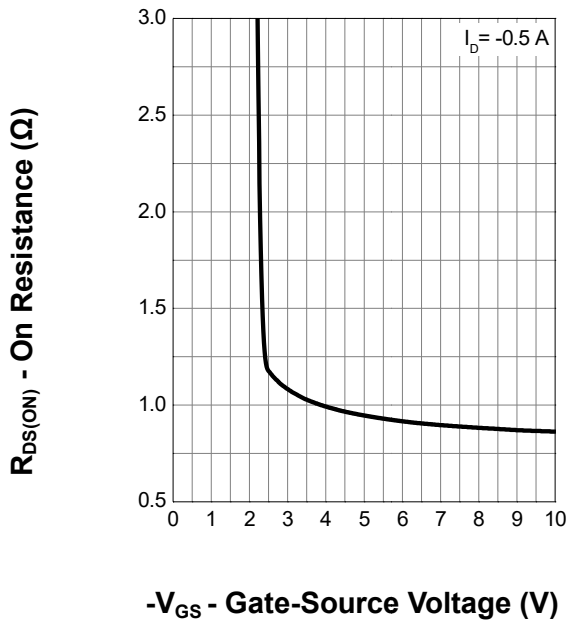
Output Characteristics



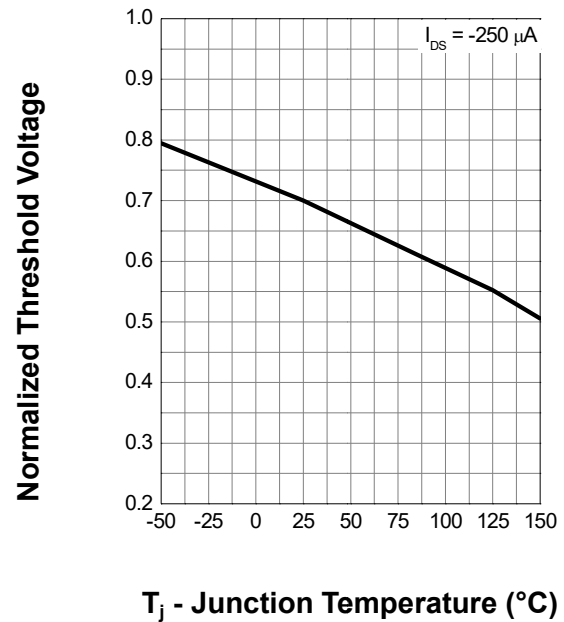
Drain-Source On Resistance



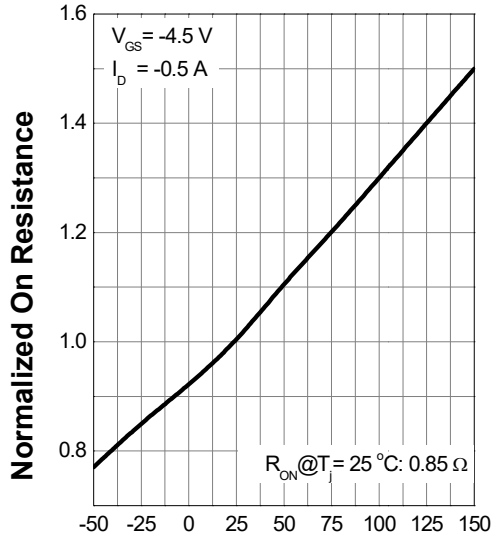
Transfer Characteristics



Gate Threshold Voltage

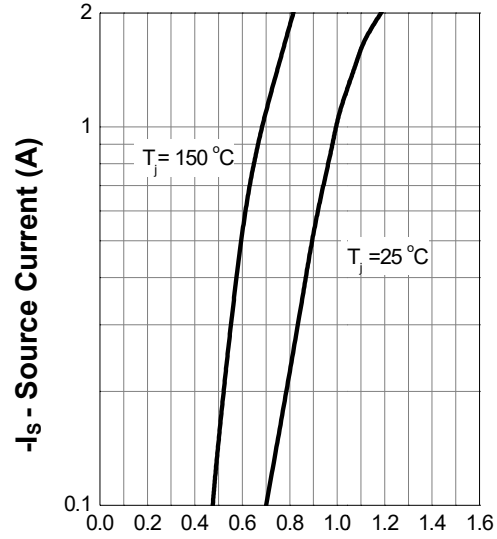


Drain-Source On Resistance



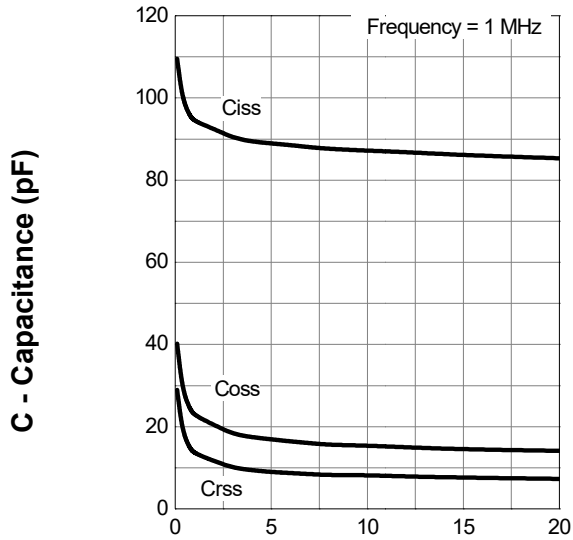
T_j - Junction Temperature ($^\circ C$)

Source-Drain Diode Forward



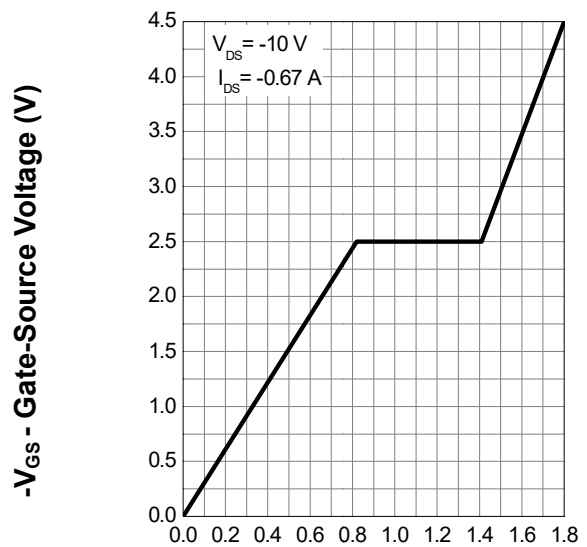
$-V_{SD}$ - Source-Drain Voltage (V)

Capacitance



$-V_{DS}$ - Drain-Source Voltage (V)

Gate Charge



Q_G - Gate Charge (pC)